

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KENICHI SAWADA	03/02/2017
RECEIVING PARTY DATA	
Name:	SUMITOMO ELECTRIC INDUSTRIES, LTD.
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State/Country:	JAPAN
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15511090
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NAME OF SUBMITTER:	KAILIE R. MACKEVERICAN
SIGNATURE:	/Kailie R. MacKeverican/
DATE SIGNED:	03/14/2017
Total Attachments: 1	
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ASSIGNMENT

Whereas, I/we,
Name

Address

1) **Kenichi SAWADA**

c/o Osaka Works of Sumitomo Electric Industries, Ltd.,
1-3, Shimaya 1-chome, Konohana-ku,
Osaka-shi, Osaka 554-0024 Japan

hereinafter called assignor(s), have invented certain improvements in
SEMICONDUCTOR MODULE

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on _____, Serial No. _____; and

Whereas

SUMITOMO ELECTRIC INDUSTRIES, LTD.
5-33, Kitahama 4-chome, Chuo-ku,
Osaka-shi, Osaka 541-0041 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORS

DATE SIGNED

1) :
Name :

Kenichi SAWADA
Kenichi SAWADA

March 2, 2017